



MB1-130-01-F-S-01-SL

MB1-130-01-F-S-01-SL-N

(1.00 mm) .0394"

MB1 SERIES

# MINI EDGE CARD SOCKET WITH GUIDES

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?MB1](http://www.samtec.com?MB1)

### Insulator Material:

Black LCP

### Contact Material:

BeCu

### Plating:

Sn or Au over  
50  $\mu$ " (1.27  $\mu$ m) Ni

### Current Rating:

2.4 A per pin  
(2 pins powered)

### Voltage Rating:

250 VDC/354 VDC

### Operating Temp Range:

-55 °C to +125 °C

### Insertion Depth:

(5.26 mm) .207" to

(6.10 mm) .240"

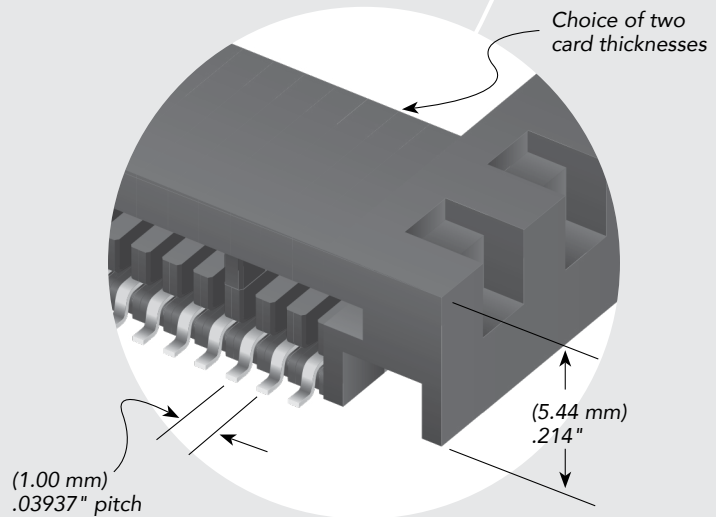
### RoHS Compliant:

Yes

### Mates with:

(0.80 mm) .031" PCB,

(1.60 mm) .062" PCB



## PROCESSING

### Lead-Free Solderable:

Yes

### SMT Lead Coplanarity:

(0.10 mm) .004" max (20-30)  
(0.15 mm) .006" max (40-50)\*

\*(.004" stencil solution may be available; contact [ipg@samtec.com](mailto:ipg@samtec.com))

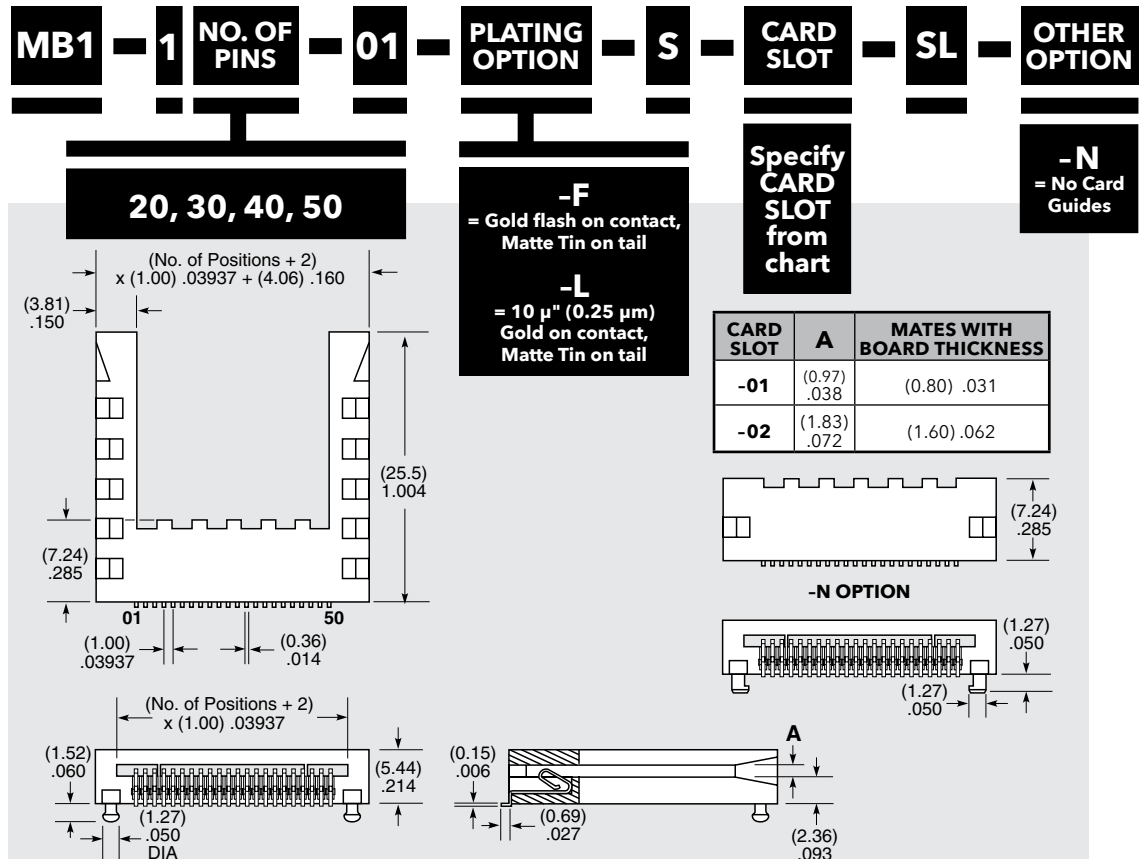
## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



## ALSO AVAILABLE (MOQ Required)

- Other platings



**Important Note:** Samtec recommends that pads on the mating board be Gold plated.